

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YUH-SEN CHANG</td> <td>02/10/2014</td> </tr> <tr> <td>SHANG-HSIEN LIN</td> <td>02/11/2014</td> </tr> <tr> <td>CHIH-YANG CHAN</td> <td>02/11/2014</td> </tr> <tr> <td>SZU-HSIEN LEE</td> <td>02/10/2014</td> </tr> <tr> <td>CHIA-HAW YEH</td> <td>02/11/2014</td> </tr> </tbody> </table>		Name	Execution Date	YUH-SEN CHANG	02/10/2014	SHANG-HSIEN LIN	02/11/2014	CHIH-YANG CHAN	02/11/2014	SZU-HSIEN LEE	02/10/2014	CHIA-HAW YEH	02/11/2014
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO.8, LI-HSIN ROAD. 6, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO.8, LI-HSIN ROAD. 6, SCIENCE-BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77		
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Application Number:	14182021												
CORRESPONDENCE DATA													
Fax Number:	(404)521-4286												
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	MCCLURE, QUALEY & RODACK, LLP												
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Address Line 2:	SUITE 200												
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ATTORNEY DOCKET NUMBER:	252011-4940												
NAME OF SUBMITTER:	DANIEL R. MCCLURE												

PATENT

Signature:	/Daniel R. McClure/
Date:	02/17/2014
Total Attachments: 2 source=00132050#page1.tif source=00132050#page2.tif	

ASSIGNMENT

WHEREAS, Yuh-Sen CHANG, Shang-Hsien LIN, Chih-Yang CHAN, Szu-Hsien LEE, and Chia-Haw YEH

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: DEVICE AND METHOD FOR WAFER TAPING

Filed: _____ Serial No. _____

Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road, 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

✓ 2014.2.10 ✓ Yuh-Sen Chang
Date Name: Yuh-Sen CHANG (Last name: CHANG)

✓ 2014.2.11 ✓ Shang-Hsien Lin
Date Name: Shang-Hsien LIN (Last name: LIN)

✓ 2014/2.11 ✓ Chih-Yang CHAN
Date Name: Chih-Yang CHAN (Last name: CHAN)

✓ 2014.2.10 ✓ Szu-Hsien Lee.
Date Name: Szu-Hsien LEE (Last name: LEE)

✓ 2014.2.11 ✓ Chia-Haw Yeh.
Date Name: Chia-Haw YEH (Last name: YEH)